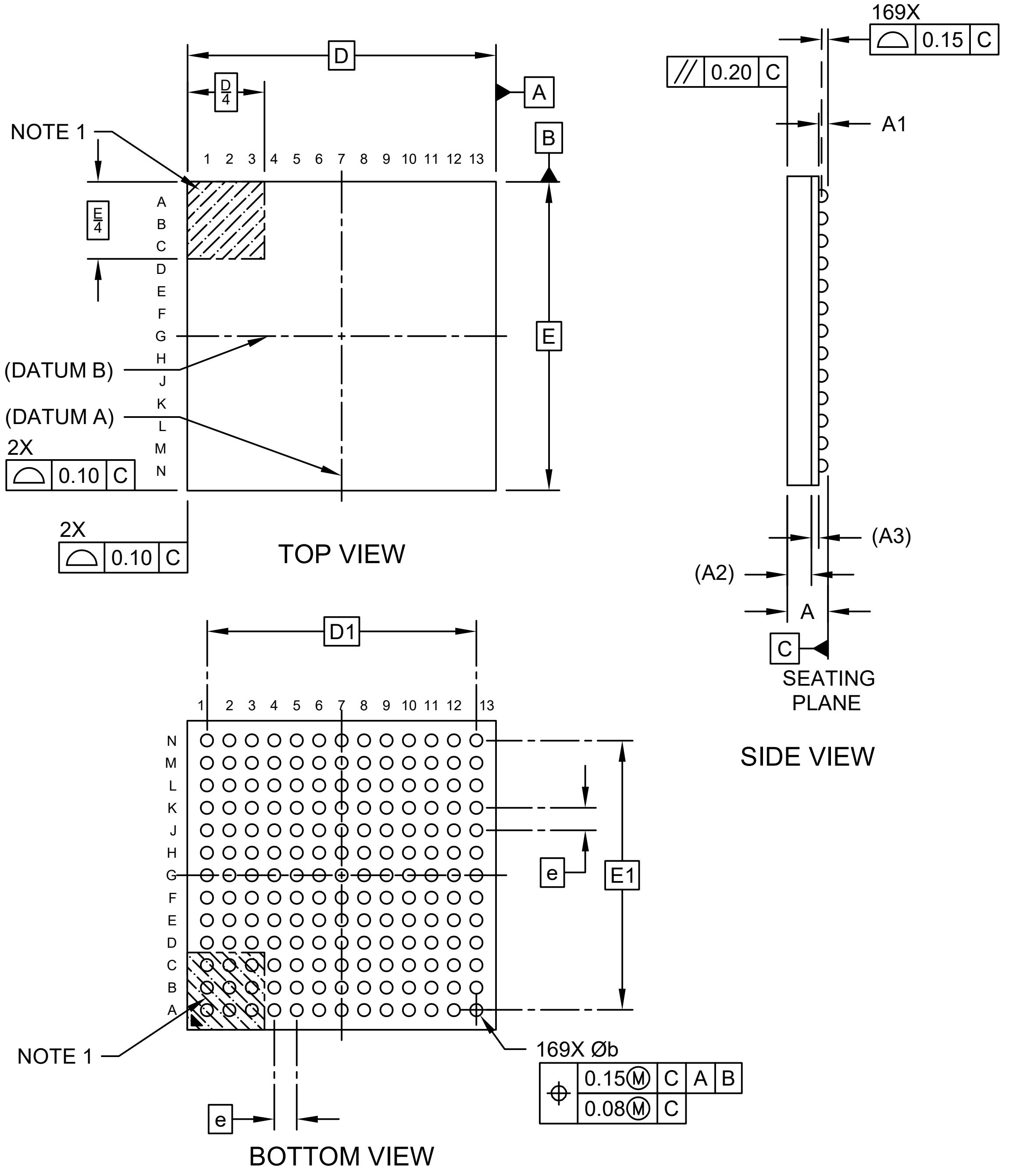
169-Ball Low Profile Ball Grid Array (6JX) - 11x11 mm Body [LFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-439-6JX Rev. C Sheet 1 of 2

169-Ball Low Profile Ball Grid Array (6JX) - 11x11 mm Body [LFBGA]

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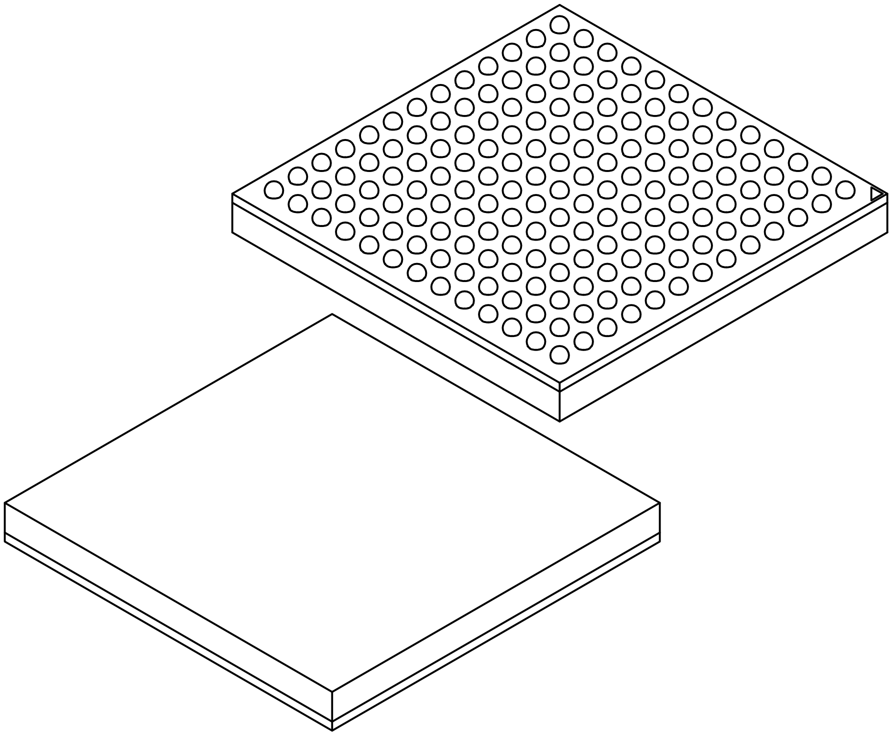

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Terminals	N		169	
Pitch	e		0.80 BSC	
Overall Height	A	1.33	1.445	1.56
Standoff	A1	0.25	-	0.40
Mold Thickness	A2		0.86 REF	
Substrate Thickness	A3		0.26 REF	
Overall Length	D		11.00 BSC	
Overall Terminal Spacing	D1		9.60 BSC	
Overall Width	E		11.00 BSC	
Overall Terminal Spacing	E1		9.60 BSC	
Terminal Diameter	b	0.40	0.45	0.50

Notes:

1. Pin A1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-439-6JX Rev. C Sheet 2 of 2

169-Ball Low Profile Ball Grid Array (6JX) - 11x11 mm Body [LFBGA]

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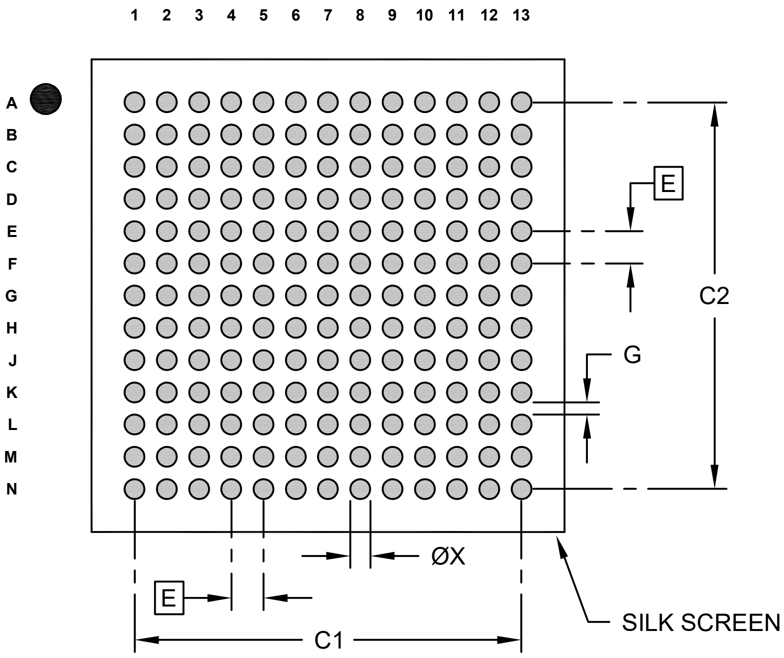


RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Overall Contact Pad Spacing	C1		9.60	
Overall Contact Pad Spacing	C2		9.60	
Contact Pad Width (X169)	X1			0.50
Contact Pad to Contact Pad	G	0.30		

Notes:

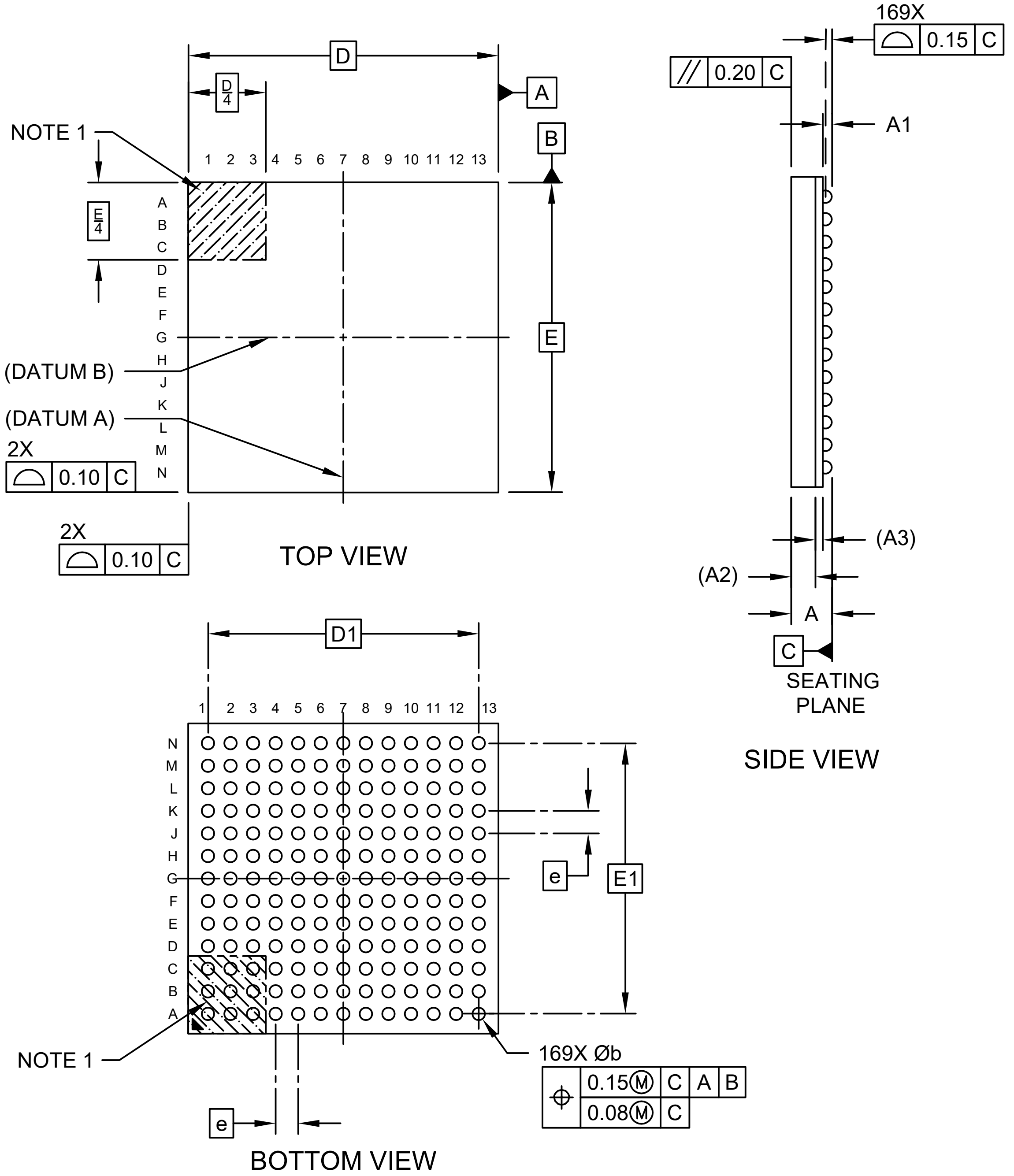
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2439-6JX Rev C

169-Ball Low Profile Ball Grid Array (6J) - 11x11 mm Body [LFBGA]

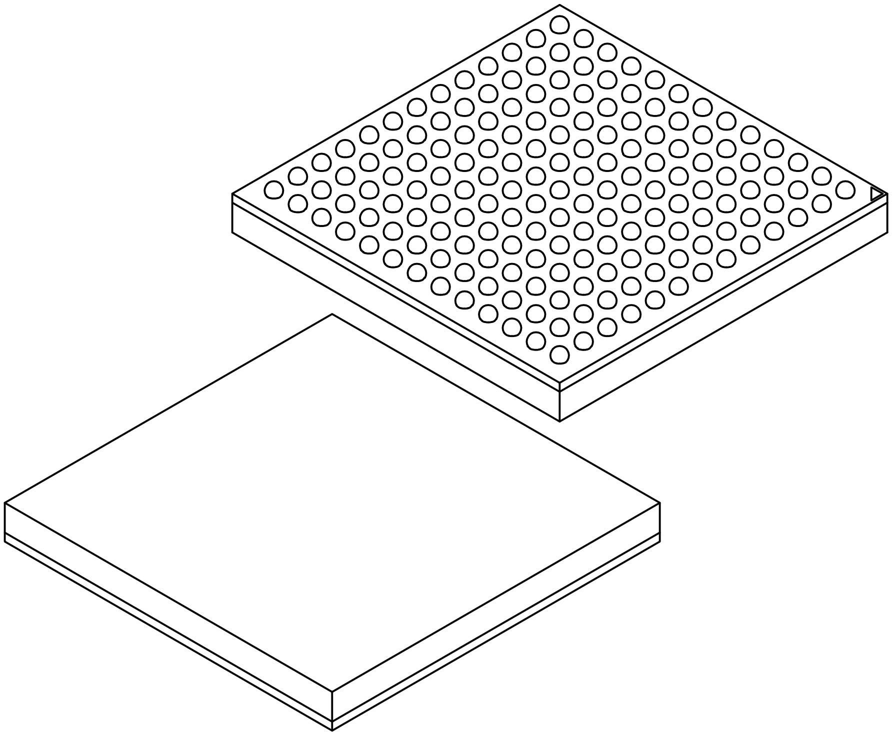
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-439-6J Rev. C Sheet 1 of 2

169-Ball Low Profile Ball Grid Array (6J) - 11x11 mm Body [LFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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Microchip Technology Drawing C04-439-6J Rev. C Sheet 2 of 2

169-Ball Low Profile Ball Grid Array (6J) - 11x11 mm Body [LFBGA]

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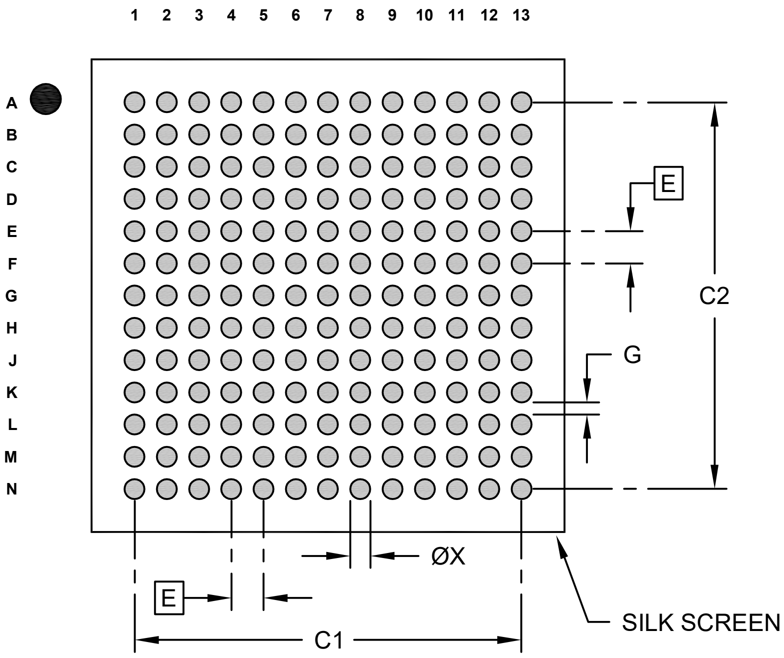

RECOMMENDED LAND PATTERN

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   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2439-6J Rev C